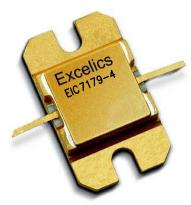


7.10-7.90GHz 4-Watt Internally-Matched Power FET

FEATURES

- 7.10-7.90GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 8.5 dB Power Gain at 1dB Compression
- 35% Power Added Efficiency
- -46 dBc IM3 at PO = 25.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}





Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 7.10-7.90GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	35.5	36.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 7.10-7.90GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	7.5	8.5		dB
ΔG	Gain Flatness $f = 7.10-7.90GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$ f = 7.10-7.90GHz		35		%
Id _{1dB}	Drain Current at 1dB Compression f = 7.10-7.90GHz		1200	1400	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10$ MHz 2-Tone Test; Pout = 25.5 dBm S.C.L ² $V_{DS} = 10$ V, $I_{DSQ} \approx 65\%$ IDSS $f = 7.90$ GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		2000	2500	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 20 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
lgf	Forward Gate Current	48mA	14.4mA	
lgr	Reverse Gate Current	-9.6mA	-2.4mA	
Pin	Input Power	36dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Storage Temperature	-65C to +175C	-65C to +175C	
Pt	Total Power Dissipation	Total Power Dissipation 25W 25W		

Note: 1. Exceeding any of the above ratings may result in permanent damage.

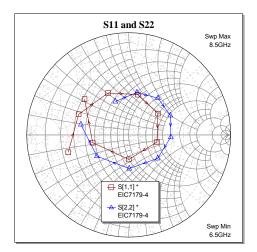
2. Exceeding any of the above ratings may reduce MTTF below design goals.

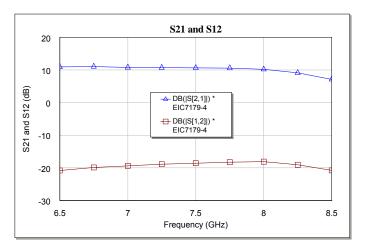


7.10-7.90GHz 4-Watt Internally-Matched Power FET

PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50 Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} \approx 1100mA



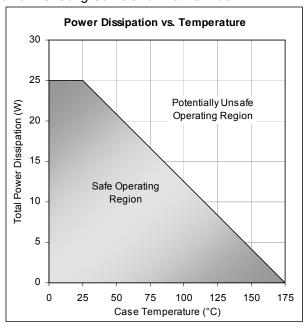


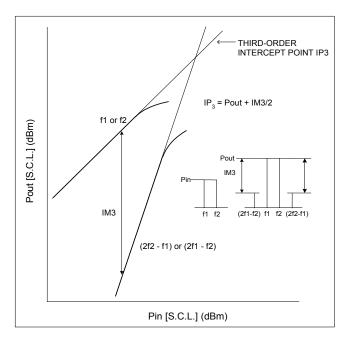
FREQ	S	S11		\$21 :		12	S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
6.25	0.717	-129.010	3.341	8.410	0.078	-50.550	0.258	158.370
6.50	0.616	-164.030	3.517	-25.170	0.091	-84.550	0.352	111.870
6.75	0.531	157.650	3.563	-58.820	0.101	-117.910	0.422	78.950
7.00	0.458	116.510	3.454	-90.850	0.107	-148.130	0.460	51.440
7.25	0.405	77.140	3.425	-121.930	0.114	-179.030	0.451	25.010
7.50	0.354	36.120	3.404	-154.300	0.118	149.090	0.413	-2.990
7.75	0.285	-14.050	3.372	171.750	0.122	117.150	0.365	-39.080
8.00	0.240	-89.650	3.238	134.430	0.125	81.280	0.329	-89.170
8.25	0.362	-167.970	2.854	95.090	0.111	42.800	0.375	-146.450
8.50	0.557	140.990	2.268	56.400	0.091	6.000	0.480	167.620
8.75	0.698	106.670	1.652	22.050	0.068	-26.910	0.568	137.060



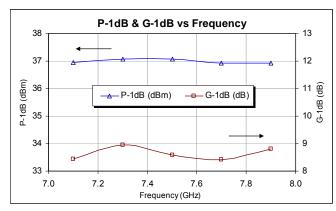
7.10-7.90GHz 4-Watt Internally-Matched Power FET

Power De-rating Curve and IM3 Definition

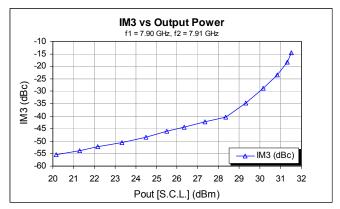




Typical Power Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} = 1100 \text{ mA}$)



Typical IM3 Data (V_{DS} = 10 V, I_{DSQ} ≈ 65% IDSS)



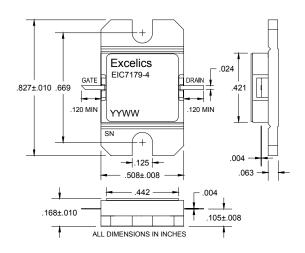


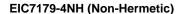
7.10-7.90GHz 4-Watt Internally-Matched Power FET

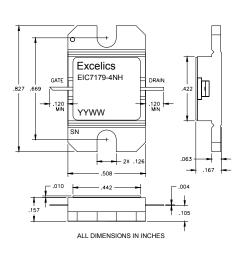
PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

EIC7179-4 (Hermetic)









Caution! ESD sensitive device.



Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC7179-4	Hermetic	Industrial	7.10-7.90GHz	35.5	-43
EIC7179-4NH	Non-Hermetic	Industrial	7.10-7.90GHz	35.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

DISCLAIMER

EXCELICS SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. EXCELICS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN.

LIFE SUPPORT POLICY

EXCELICS SEMICONDUCTOR PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF EXCELICS SEMICONDUCTOR. INC. AS HERE IN:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness